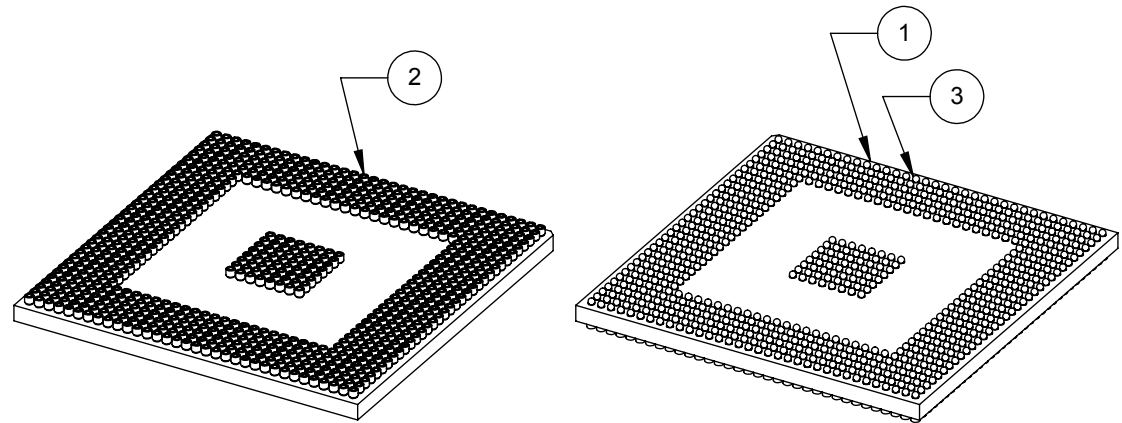
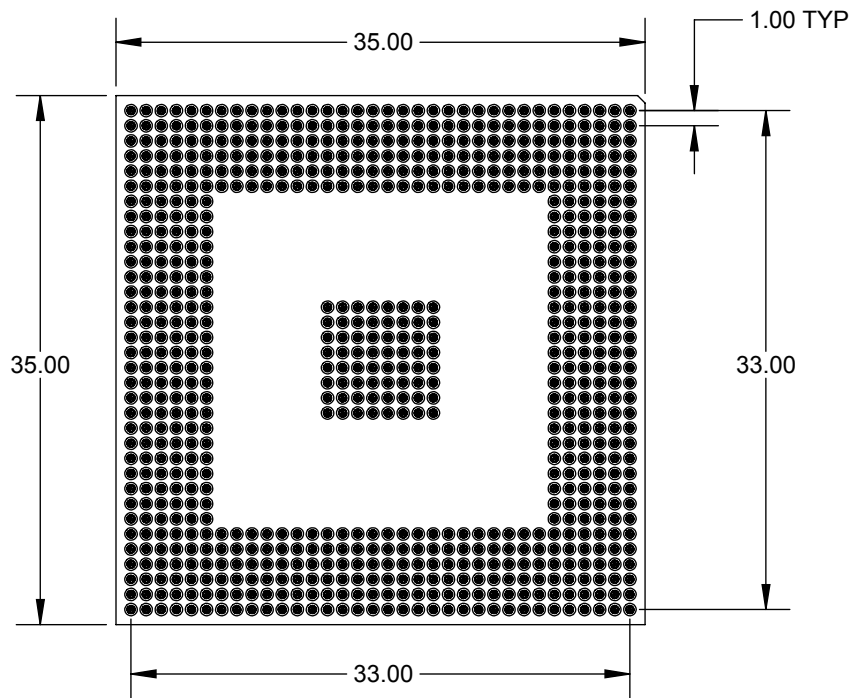
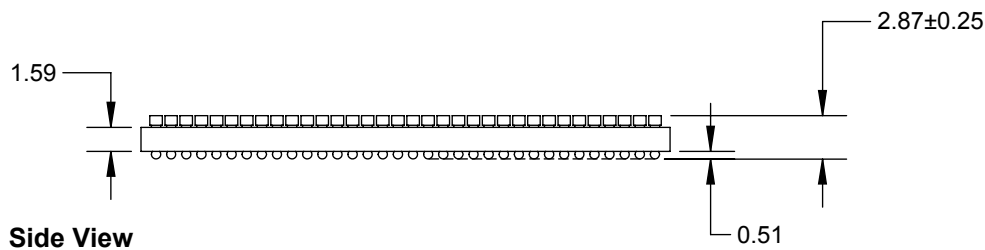


U.S. Patent No. 8,091,222 B2



Top View



Side View


ITEM NO.	DESCRIPTION
1	High temperature substrate
2	Socket receptacle Pin, 1.0mm centers minimum, 3 finger clip
3	Solder Ball, 0.024" Dia

PART NO. SUFFIX	SOLDER BALL ALLOY
-42	Sn63Pb37
-42F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

Description: SF-BGA724A-B-42, 35mm, 1.0mm pitch, 34x34 array

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA724A-B-42 Drawing SF-BGA724A-B-42F Drawing	Material: N/A Finish: N/A Weight: N/A	STATUS: Released	SHEET: 1 OF 1	REV. A
		ENG: J. Vavra	SCALE: 2:1	
 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		FILE: SF-BGA724A-B-42 Dwg	DATE: 04/24/2015	